## $18 \times 11$ DOTS MATRIX LED DRIVER

April 2022

## GENERAL DESCRIPTION

The IS31FL3743A is a general purpose $18 \times n$ ( $n=1 \sim 11$ ) LED Matrix programmed via 1 MHz I2C compatible interface. Each LED can be dimmed individually with 8-bit PWM data and 8-bit DC scaling data which allowing 256 steps of linear PWM dimming and 256 steps of DC current adjustable level.
Additionally each LED open and short state can be detected, IS31FL3743A store the open or short information in Open-Short Registers. The Open-Short Registers allowing MCU to read out via I2C compatible interface, inform MCU whether there are LEDs open or short and the locations of open or short LEDs.

The IS31FL3743A operates from 2.7 V to 5.5 V and features a very low shutdown and operational current.

IS31FL3743A is available in UQFN-40 ( $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ ) package. It operates from 2.7 V to 5.5 V over the temperature range of $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$.

## FEATURES

- Supply voltage range: 2.7 V to 5.5 V
- 18 current sinks
- Support $18 \times n$ ( $n=1 \sim 11$ ) LED matrix configurations
- Individual 256 PWM control steps
- Individual 256 DC current steps
- Global 256 DC current steps
- SDB rising edge reset I2C module
- Programmable H/L logic: $1.4 \mathrm{~V} / 0.4 \mathrm{~V}, 2.4 \mathrm{~V} / 0.6 \mathrm{~V}$
- 24kHz PWM frequency
- 1 MHz I2C-compatible interface
- State lookup registers
- Individual open and short error detect function
- 180 degree phase delay operation to reduce power noise
- De-Ghost
- Cascade for synchronization of chips
- UQFN-40 ( $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ ) package


## APPLICATIONS

- Hand-held devices for LED display
- Gaming device (Keyboard, Mouse etc.)
- LED in white goods application


## TYPICAL APPLICATION CIRCUIT



Figure 1 Typical Application Circuit: 66 RGBs
Note 1: For the mobile applications the IC should be placed far away from the mobile antenna in order to prevent the EMI.
Note 2: PVCC and VCC should use same power supply to avoid the additional $\mathrm{I}_{\mathrm{SD}}$, it is OK to use $\mathrm{PV} \mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$ and $\mathrm{V}_{10}=3.3 \mathrm{~V}$.

TYPICAL APPLICATION CIRCUIT (CONTINUED)


Figure 2 Typical Application Circuit: 198 Mono Color LEDs


Figure 3 Typical Application Circuit (Eight Parts Synchronization-Work)
Note 3: The 20R and 50R between LED and IC is only for thermal reduction, for mono red LED, if $P V_{C C}=V_{C C}=3.3 V$, don't need these resistors.
Note 4: One part is configured as master mode, all the other 7 parts configured as slave mode. Work as master mode or slave mode specified by Configuration Register (SYNC bits, register 25h, Page 2). Master part output master clock, and all the other parts which work as slave input this master clock.

PIN CONFIGURATION

| Package | Pin Configuration (Top View) |
| :---: | :---: |
| UQFN-40 |  |

## PIN DESCRIPTION

| No. | Pin | Description |
| :--- | :--- | :--- |
| $1 \sim 4$ | SW8,SW6,SW4,SW2 | Power SW. |
| 5 | PVCC | Power for current source SW. |
| $6 \sim 11$ | SW1,SW3,SW5, <br> SW7,SW9,SW11 | Power SW. |
| $12 \sim 15$ | CS18~CS15 | Current sink pin for LED matrix. |
| 16 | PGND | Power GND. |
| $17 \sim 21$ | CS14~CS10 | Current sink pin for LED matrix. |
| 22 | GCC | Analog and digital circuits. |
| 23 | GND | Analog GND. |
| 24 | ADDR1 | I2C address select pin 2. |
| 25 | SDB | I2C address select pin 1. |
| 26 | SDA | Shutdown pin. |
| 27 | ISET | I2C compatible serial clock. |
| 28 | SYNC | I2C compatible serial data. |
| 29 | CS9~CS1 | Set the maximum IOUT current. |
| 30 | SW10 | Synchronization. |
| $31 \sim 39$ | Thermal Pad | Current sink pin for LED matrix. |
| 40 | Power SW. |  |
|  | Connect to GND. |  |

ORDERING INFORMATION
Industrial Range: $-40^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$

| Order Part No. | Package | QTY/Reel |
| :--- | :--- | :--- |
| IS31FL3743A-QULS4-TR | UQFN-40, Lead-free | 2500 |

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ABSOLUTE MAXIMUM RATINGS

| Supply voltage, $\mathrm{V}_{\mathrm{CC}}$ | $-0.3 \mathrm{~V} \sim+6.0 \mathrm{~V}$ |
| :--- | :--- |
| Voltage at any input pin | $-0.3 \mathrm{~V} \sim \mathrm{VCC}+0.3 \mathrm{~V}$ |
| Maximum junction temperature, $\mathrm{T}_{\mathrm{JMAX}}$ | $+150^{\circ} \mathrm{C}$ |
| Storage temperature range, $\mathrm{T}_{\text {STG }}$ | $-65^{\circ} \mathrm{C} \sim+150^{\circ} \mathrm{C}$ |
| Operating temperature range, $\mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{J}}$ | $-40^{\circ} \mathrm{C} \sim+125^{\circ} \mathrm{C}$ |
| Package thermal resistance, junction to ambient (4-layer standard test PCB based <br> on JESD 51-2A), $\theta_{\mathrm{JA}}$ | $41.6^{\circ} \mathrm{C} / \mathrm{W}$ |
| ESD (HBM) <br> ESD (CDM) | $\pm 7 \mathrm{kV}$ |
| $\pm 1 \mathrm{kV}$ |  |

Note 5: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS
The following specifications apply for $\mathrm{V}_{\mathrm{CC}}=3.6 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Vcc | Supply voltage |  | 2.7 |  | 5.5 | V |
| Icc | Quiescent power supply current | $\mathrm{V}_{\text {sdB }}=\mathrm{V}_{\mathrm{cc}}$, all LEDs off |  | 1.8 |  | mA |
| ISD | Shutdown current | $V_{\text {SDB }}=0 \mathrm{~V}$ |  | 1.3 |  | $\mu \mathrm{A}$ |
|  |  | $\mathrm{V}_{\mathrm{sdB}}=\mathrm{V}_{\mathrm{cc}}$, Configuration Register written "0000 0000 |  | 1.3 |  |  |
| lout | Maximum constant current of CSy | $\begin{aligned} & \text { RISET=10k } \Omega, G C C=0 x F F \\ & S L=0 x F F \end{aligned}$ | 32.09 | 34.5 | 36.91 | mA |
| Iled | Average current on each LED ILED $=$ Iout(PEAK)/Duty (11.275) | $\begin{aligned} & \text { RISET }=10 \mathrm{k} \Omega, \mathrm{GCC}=0 \times \mathrm{FF} \\ & \mathrm{SL}=0 \times \mathrm{FF} \end{aligned}$ |  | 3.03 |  | mA |
| $V_{\text {HR }}$ | Current switch headroom voltage SWx | $\begin{aligned} & \text { ISWITCH }=612 \mathrm{~mA} R_{\text {ISET }}=10 \mathrm{k} \Omega, \\ & \text { GCC=0xFF, SL=0xFF } \end{aligned}$ |  | 550 |  | mV |
|  | Current sink headroom voltage CSy | $\begin{aligned} & I_{\text {SINK }}=34 \mathrm{~mA}, \mathrm{R}_{\mathrm{ISET}}=10 \mathrm{k} \Omega \text {, } \\ & \mathrm{GCC}=0 \times F F, \mathrm{SL}=0 \times F F \end{aligned}$ |  | 450 |  |  |
| tscan | Period of scanning |  |  | 33 |  | $\mu \mathrm{s}$ |
| $t_{\text {NOL1 }}$ | Non-overlap blanking time during scan, the SWx and CSy are all off during this time |  |  | 0.83 |  | $\mu \mathrm{s}$ |
| $t_{\text {NoL2 }}$ | Delay total time for CS1 to CS 18 , during this time, the SWx is on but CSy is not all turned on |  |  | 0.3 |  | $\mu \mathrm{s}$ |

Logic Electrical Characteristics (SDA, SCL, ADDRx, SDB)

| VIL | Logic "0" input voltage | $\mathrm{V}_{\mathrm{cc}}=2.7 \mathrm{~V} \sim 5.5 \mathrm{~V}$, LGC=0 |  |  | 0.4 | V |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| VIH | Logic "1" input voltage | $\mathrm{V}_{\mathrm{cc}}=2.7 \mathrm{~V} \sim 5.5 \mathrm{~V}$, LGC=0 | 1.4 |  |  | V |
| $\mathrm{V}_{\mathrm{HYS}}$ | Input schmitt trigger hysteresis | $\mathrm{Vcc}=3.6 \mathrm{~V}$, LGC=0 |  | 0.2 |  | V |
| VIL | Logic "0" input voltage | $\mathrm{V}_{\mathrm{cc}}=2.7 \mathrm{~V} \sim 5.5 \mathrm{~V}$, LGC=1 |  |  | 0.6 | V |
| VIH | Logic "1" input voltage | $\mathrm{V}_{\mathrm{cc}}=2.7 \mathrm{~V} \sim 5.5 \mathrm{~V}$, LGC=1 | 2.4 |  |  | V |
| V HYS | Input schmitt trigger hysteresis | $\mathrm{V}_{\mathrm{cc}}=3.6 \mathrm{~V}$, LGC=1 |  | 0.2 |  | V |
| IIL | Logic "0" input current | SDB=L, $\mathrm{V}_{\text {InPut }}=\mathrm{L}($ Note 6) |  | 5 |  | nA |
| $\mathrm{IIH}^{\text {H }}$ | Logic "1" input current | SDB=L, $\mathrm{V}_{\text {Input }}=\mathrm{H}($ Note 6) |  | 5 |  | nA |

DIGITAL INPUT I2C SWITCHING CHARACTERISTICS (NOTE 6)

| Symbol | Parameter | Fast Mode |  |  | Fast Mode Plus |  |  | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max. | Min. | Typ. | Max. |  |
| fsCL | Serial-clock frequency | - |  | 400 | - |  | 1000 | kHz |
| $t_{\text {buF }}$ | Bus free time between a STOP and a START condition | 1.3 |  | - | 0.5 |  | - | $\mu \mathrm{s}$ |
| $\mathrm{thD}^{\text {, STA }}$ | Hold time (repeated) START condition | 0.6 |  | - | 0.26 |  | - | $\mu \mathrm{s}$ |
| tsu, sta | Repeated START condition setup time | 0.6 |  | - | 0.26 |  | - | $\mu \mathrm{s}$ |
| tsu, sto | STOP condition setup time | 0.6 |  | - | 0.26 |  | - | $\mu \mathrm{s}$ |
| thd, DAT | Data hold time | - |  | - | - |  | - | $\mu \mathrm{s}$ |
| tsu, DAT | Data setup time | 100 |  | - | 50 |  | - | ns |
| tıow | SCL clock low period | 1.3 |  | - | 0.5 |  | - | $\mu \mathrm{s}$ |
| thigh | SCL clock high period | 0.7 |  | - | 0.26 |  | - | $\mu \mathrm{s}$ |
| $t_{R}$ | Rise time of both SDA and SCL signals, receiving | - |  | 300 | - |  | 120 | ns |
| $t_{\text {F }}$ | Fall time of both SDA and SCL signals, receiving | - |  | 300 | - |  | 120 | ns |

[^0]FUNCTIONAL BLOCK DIAGRAM


## DETAILED DESCRIPTION

## I2C INTERFACE

IS31FL3743A uses a serial bus, which conforms to the I2C protocol, to control the chip's functions with two wires: SCL and SDA. The IS31FL3743A has a 7-bit slave address (A7:A1), followed by the R/W bit, A0. Set A0 to " 0 " for a write command and set A 0 to " 1 " for a read command. The value of bits A1 and A2 are decided by the connection of the ADDRx pin.

Table 1 Slave Address:

| ADDR2 | ADDR1 | A7:A5 | A4:A3 | A2:A1 | A0 |
| :---: | :---: | :---: | :---: | :---: | :---: |
| GND | GND | 010 | 00 | 00 | 0/1 |
| GND | SCL |  | 00 | 01 |  |
| GND | SDA |  | 00 | 10 |  |
| GND | VCC |  | 00 | 11 |  |
| SCL | GND |  | 01 | 00 |  |
| SCL | SCL |  | 01 | 01 |  |
| SCL | SDA |  | 01 | 10 |  |
| SCL | VCC |  | 01 | 11 |  |
| SDA | GND |  | 10 | 00 |  |
| SDA | SCL |  | 10 | 01 |  |
| SDA | SDA |  | 10 | 10 |  |
| SDA | VCC |  | 10 | 11 |  |
| VCC | GND |  | 11 | 00 |  |
| VCC | SCL |  | 11 | 01 |  |
| VCC | SDA |  | 11 | 10 |  |
| VCC | VCC |  | 11 | 11 |  |

ADDR1/2 connected to GND, (A2:A1)/(A4:A3)=00; ADDR1/2 connected to VCC, (A2:A1)/(A4:A3)=11; ADDR1/2 connected to SCL, (A2:A1)/(A4:A3)=01; ADDR1/2 connected to SDA, (A2:A1)/(A4:A3)=10;

The SCL line is uni-directional. The SDA line is bidirectional (open-drain) with a pull-up resistor (typically 400 kHz I2C with $4.7 \mathrm{k} \Omega, 1 \mathrm{MHz} \mathrm{I} 2 \mathrm{C}$ with $2 \mathrm{k} \Omega$ ). The maximum clock frequency specified by the I2C standard is 1 MHz . In this discussion, the master is the microcontroller and the slave is the IS31FL3743A.

The timing diagram for the I2C is shown in Figure 4. The SDA is latched in on the stable high level of the SCL. When there is no interface activity, the SDA line should be held high.

The "START" signal is generated by lowering the SDA signal while the SCL signal is high. The start signal will alert all devices attached to the I2C bus to check the incoming address against their own chip address.

The 8-bit chip address is sent next, most significant bit first. Each address bit must be stable while the SCL level is high.

After the last bit of the chip address is sent, the master checks for the IS31FL3743A's acknowledge. The master releases the SDA line high (through a pull-up resistor). Then the master sends an SCL pulse. If the IS31FL3743A has received the address correctly, then it holds the SDA line low during the SCL pulse. If the SDA line is not low, then the master should send a "STOP" signal (discussed later) and abort the transfer.

Following acknowledge of IS31FL3743A, the register address byte is sent, most significant bit first. IS31FL3743A must generate another acknowledge indicating that the register address has been received.

Then 8-bit of data byte are sent next, most significant bit first. Each data bit should be valid while the SCL level is stable high. After the data byte is sent, the IS31FL3743A must generate another acknowledge to indicate that the data was received.
The "STOP" signal ends the transfer. To signal "STOP", the SDA signal goes high while the SCL signal is high.

## ADDRESS AUTO INCREMENT

To write multiple bytes of data into IS31FL3743A, load the address of the data register that the first data byte is intended for. During the IS31FL3743A acknowledge of receiving the data byte, the internal address pointer will increment by one. The next data byte sent to IS31FL3743A will be placed in the new address, and so on. The auto increment of the address will continue as long as data continues to be written to IS31FL3743A (Figure 7).

## READING OPERATION

Most of the registers can be read.
To read the FCh, FEh, after I2C start condition, the bus master must send the IS31FL3743A device address with the R/W bit set to "0", followed by the register address (FEh or F1h) which determines which register is accessed. Then restart I2C, the bus master should send the IS31FL3743A device address with the $\mathrm{R} / \overline{\mathrm{W}}$ bit set to " 1 ". Data from the register defined by the command byte is then sent from the IS31FL3743A to the master (Figure 8).
To read the registers of Page 0 thru Page 3, the FDh should write with 00 h before follow the Figure 8 sequence to read the data. That means, when you want to read registers of Page 0 , the FDh should point to Page 0 first and you can read the Page 0 data.


Figure 4 I2C Interface Timing
SDA $\quad \mathrm{SCL}$

Figure 5 I2C Bit Transfer

|  |  |  |  |  |  |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  |  |  |  |  |  |  |  |  |

Figure 6 I2C Writing to IS31FL3743A (Typical)


Figure 7 I2C Writing to IS31FL3743A (Automatic Address Increment)


Figure 8 I2C Reading from IS31FL3743A

Table 2 Command Register Definition

| Address | Name | Function | Table | R/W | Default |
| :---: | :--- | :--- | :---: | :---: | :---: |
| FEh | Command Register Write Lock | To unlock Command Register | 4 | R/W | 00000000 |
| FDh | Command Register | Available Page 0 to Page 2 Registers | 3 | W | xxxx xxxx |
| FCh | ID Register | For read the product ID only <br> Read result is the slave address | - | R | Slave <br> Address |

## REGISTER CONTROL



Table 3 FDh Command Register

| Data | Function |
| :---: | :--- |
| 00000000 | Point to Page 0 (PG0, PWM Register is available) |
| 00000001 | Point to Page 1 (PG1, White balance Scaling Register is available) |
| 00000010 | Point to Page 2 (PG2, Function Register is available) |
| Others | Reserved |

Note: FDh is locked when power up, need to unlock this register before write command to it. See Table 4 for detail.
The Command Register should be configured first after writing in the slave address to choose the available register. Then write data in the choosing register. Power up default state is "0000 0000".
For example, when write "0000 0001" in the Command Register (FDh), the data which writing after will be stored in the White balance Scaling Register. Write new data can configure other registers.

Table 4 FEh Command Register Write Lock (Read/Write)

| Bit | D7:D0 |
| :---: | :---: |
| Name | CRWL |
| Default | 00000000 (FDh write disable) |

To select the PG0~PG2, need to unlock this register first, with the purpose to avoid mis-operation of this register. When FEh is written with $0 x C 5$, FDh is allowed to modify once, after the FDh is modified the FEh will reset to be $0 \times 00$ at once.

Table 5 Register Definition

| Address | Name | Function | Table | R/W | Default |
| :---: | :---: | :---: | :---: | :---: | :---: |
| PG0 (0x00): PWM Register |  |  |  |  |  |
| 01h~C6h | PWM Register | Set PWM for each LED | 6 | R/W | 00000000 |
| PG1 (0x01): LED Scaling |  |  |  |  |  |
| 01h~C6h | Scaling Register | Set Scaling for each LED | 7 | R/W | 00000000 |
| PG2 (0x02): Function Register |  |  |  |  |  |
| 00h | Configuration Register | Configure the operation mode | 9 | R/W | 00000000 |
| 01h | Global Current Control Register | Set the global current | 10 | R/W | 00000000 |
| 02h | Pull Down/Up Resistor Selection Register | Set the pull-down resistor for SWx and pull up resistor for CSy | 11 | R/W | 00110011 |
| 03h~23h | Open/Short Register | Store the open or short information | 12 | R | 00000000 |
| 24h | Temperature Status | Store the temperature point of the IC | 13 | R/W | 00000000 |
| 25h | Spread Spectrum Register | Spread spectrum function enable | 14 | R/W | 00000000 |
| 2Fh | Reset Register | Reset all register to POR state | - | W | 00000000 |

Page 0 (PG0, FDh= 0x00): PWM Register


Figure 9 PWM Register

Table 6 PG0: 01h~C6h PWM Register

| Bit | D7:D0 |
| :---: | :---: |
| Name | PWM |
| Default | 00000000 |

Each dot has a byte to modulate the PWM duty in 256 steps.
The value of the PWM Registers decides the average current of each LED noted ILED.
lled computed by Formula (1):

$$
\begin{gather*}
I_{\text {LED }}=\frac{P W M}{256} \times I_{\text {OUT (PEAK })} \times \text { Duty }  \tag{1}\\
P W M=\sum_{n=0}^{7} D[n] \cdot 2^{n}
\end{gather*}
$$

Where Duty is the duty cycle of SWx, see SCANING TIMING section for more information.

$$
\begin{equation*}
\text { Duty }=\frac{33 \mu s}{(33 \mu s+0.83 \mu s+0.3 \mu s)} \times \frac{1}{11}=\frac{1}{11.377} \tag{2}
\end{equation*}
$$

lout is the output current of CSy $(y=1 \sim 18)$,

$$
\begin{equation*}
I_{O U T(P E A K)}=\frac{343}{R_{I S E T}} \times \frac{G C C}{256} \times \frac{S L}{256} \tag{3}
\end{equation*}
$$

GCC is the Global Current Control register (PG2, 01 h ) value, SL is the Scaling Register value as Table 9 and $\mathrm{R}_{\text {ISET }}$ is the external resistor of ISET pin. $\mathrm{D}[\mathrm{n}]$ stands for the individual bit value, 1 or 0 , in location n.

For example: if $D 7: D 0=10110101$ ( $0 x B 5,181$ ), GCC=1111 1111, R ${ }_{\text {ISET }}=10 k \Omega, S L=1111$ 1111:

$$
I_{\text {LED }}=\frac{343}{10 k \Omega} \times \frac{255}{256} \times \frac{255}{256} \times \frac{1}{11.377} \times \frac{181}{256}
$$

Page 1 (PG1, FDh= 0x01): Scaling Register


Figure 10 Scaling Register

Table 7 PG1: 01h~C6h Scaling Register

| Bit | D7:D0 |
| :---: | :---: |
| Name | SL |
| Default | 00000000 |

Scaling register control the DC output current of each dot. Each dot has a byte to modulate the scaling in 256 steps.

The value of the Scaling Register decides the peak current of each LED noted lout(PEAK).
Iout(PEAK) computed by Formula (3):

$$
\begin{array}{r}
I_{\text {OUT(PEAK) }}=\frac{343}{R_{\text {ISET }}} \times \frac{G C C}{256} \times \frac{S L}{256} \\
\mathrm{~S} L
\end{array}=\sum_{n=0}^{7} D[n] \cdot 2^{n}
$$

lout is the output current of CSy ( $\mathrm{y}=1 \sim 18$ ), GCC is the Global Current Control Register (PG2, 01h) value and $\mathrm{R}_{\text {ISET }}$ is the external resistor of ISET pin. $D[n]$ stands for the individual bit value, 1 or 0 , in location $n$.

For example: if RISET=10k $\Omega, \quad G C C=1111$ 1111, SL=0111 1111:

$$
\begin{gathered}
\mathrm{S} L=\sum_{n=0}^{7} D[n] \cdot 2^{n}=127 \\
I_{\text {OUT }}=\frac{343}{10 k \Omega} \times \frac{255}{256} \times \frac{127}{256}=16.8 \mathrm{~mA} \\
I_{\text {LED }}=16.8 \mathrm{~mA} \times \frac{1}{11.377} \times \frac{P W M}{256}
\end{gathered}
$$

Table 8 Page 2 (PG2, FDh= 0x02): Function Register

| Register | Name | Function | Table | R/W | Default |
| :---: | :--- | :--- | :---: | :---: | :---: |
| 00h | Configuration Register | Configure the operation mode | 10 | R/W | 00001000 |
| 01h | Global Current Control <br> Register | Set the global current | 11 | R/W | 00000000 |
| 02 h | Pull Down/Up Resistor <br> Selection Register | Set the pull-down resistor for SWx <br> and pull up resistor for CSy | 12 | R/W | 00110011 |
| 03h~23h | Open/Short Register | Store the open or short information | 13 | R | 00000000 |
| 24 h | Temperature Status | Store the temperature point of the IC | 14 | R/W | 00000000 |
| 25 h | Spread Spectrum Register | Spread spectrum function enable | 15 | R/W | 00000000 |
| 2 2Fh | Reset Register | Reset all register to POR state | - | W | 00000000 |

Table 9 00h Configuration Register

| Bit | D7:D4 | D3 | D2:D1 | D0 |
| :---: | :---: | :---: | :---: | :---: |
| Name | SWS | LGC | OSDE | SSD |
| Default | 0000 | 1 | 00 | 0 |

The Configuration Register sets operating mode of IS31FL3743A.
When OSDE set to " 01 ", open detection will be trigger once, the user could trigger open detection again by set OSDE from "00" to "01".
Before set OSDE, the GCC should set to 0x0F, please check OPEN/SHORT DETECT FUNCTION section for more information.
When SSD is "0", IS31FL3743A works in software shutdown mode and to normal operate the SSD bit should set to " 1 ". SWS control the duty cycle of the SW, default mode is $1 / 11$.

| SSD | Software Shutdown Control |
| :--- | :--- |
| 0 | Software shutdown |
| 1 | Normal operation |
|  |  |
| LGC | H/L Logic |
| 0 | $1.4 \mathrm{~V} / 0.4 \mathrm{~V}$ |
| 1 | $2.4 \mathrm{~V} / 0.6 \mathrm{~V}$ |

OSDE Open Detection Enable
00/11 Disable open/short detection
01 Enable open detection
10 Enable short detection
SWS SWx Setting
0000 SW1~SW11, 1/11
0001 SW1~SW10, 1/10, SW11 no-active
0010 SW1~SW9, 1/9, SW10~SW11 no-active
0011 SW1~SW8, 1/8, SW9~SW11 no-active
0100 SW1~SW7, 1/7, SW8~SW11 no-active
0101 SW1~SW6, 1/6, SW7~SW11 no-active
0110 SW1~SW5, 1/5, SW6~SW11 no-active

0111 SW1~SW4, 1/4, SW5~SW11 no-active
1000 SW1~SW3, 1/3, SW4~SW11 no-active
1001 SW1~SW2, 1/2, SW3~SW11 no-active
1010 All CSy work as current sinks only, no scan Others Not allowed

Table 10 01h Global Current Control Register

| Bit | D7:D0 |
| :---: | :---: |
| Name | GCC |
| Default | 00000000 |

The Global Current Control Register modulates all CSy ( $\mathrm{y}=1 \sim 18$ ) DC current which is noted as lout in 256 steps.
lout is computed by the Formula (3):

$$
I_{\text {OUT(PEAK })}=\frac{343}{R_{I S E T}} \times \frac{G C C}{256} \times \frac{S L}{256}
$$

$$
G C C=\sum_{n=0}^{7} D[n] \cdot 2^{n}
$$

Where $D[n]$ stands for the individual bit value, 1 or 0 , in location n .

Table 11 02h Pull Down/Up Resistor Selection Register

| Bit | D7 | D6:D4 | D3 | D2:D0 |
| :---: | :---: | :---: | :---: | :---: |
| Name | PHC | SWPDR | - | CSPUR |
| Default | 0 | 011 | 0 | 011 |

Set pull down resistor for SWx and pull up resistor for CSy.
Please check DE-GHOST FUNCTION section for more information.

```
PHC Phase choice
0 degree phase delay
180 degree phase delay
```

SWPDR SWx Pull down Resistor Selection Bit
000 No pull down resistor
$001 \quad 0.5 \mathrm{k} \Omega$ only in SWx off time
$010 \quad 1.0 \mathrm{k} \Omega$ only in $\mathrm{SW} x$ off time
$0112.0 \mathrm{k} \Omega$ only in SWx off time
$100 \quad 1.0 \mathrm{k} \Omega$ all the time
$1012.0 \mathrm{k} \Omega$ all the time
$1104.0 \mathrm{k} \Omega$ all the time
$1118.0 \mathrm{k} \Omega$ all the time

CSPUR CSy Pull up Resistor Selection Bit
000 No pull up resistor
$001 \quad 0.5 \mathrm{k} \Omega$ only in CSy off time
$010 \quad 1.0 \mathrm{k} \Omega$ only in CSy off time
$0112.0 \mathrm{k} \Omega$ only in CSy off time
$100 \quad 1.0 \mathrm{k} \Omega$ all the time
$1012.0 \mathrm{k} \Omega$ all the time
$110 \quad 4.0 \mathrm{k} \Omega$ all the time
$1118.0 \mathrm{k} \Omega$ all the time
Table 12 Open/Short Register (Read Only)
03h~23h Open/Short Information

| Bit | D7:D6 | D5:D0 |
| :---: | :---: | :---: |
| Name | - | CS18:CS13, <br> CS12:CS07,CS06:CS01 |
| Default | 00 | 000000 |

When OSDE (PG2, 00h) is set to "01", open detection will be trigger once, and the open information will be stored at 03h~23h.
When OSDE (PG2, 00h) set to " 10 ", short detection will be trigger once, and the short information will be stored at 03h~23h.
Before set OSDE, the GCC should set to 0x0F, please check OPEN/SHORT DETECT FUNCTION section for more information.


Figure 11 Open/Short Register

Table 13 24h Temperature Status

| Bit | D7:D4 | D3:D2 | D1:D0 |
| :---: | :---: | :---: | :---: |
| Name | - | TS | TROF |
| Default | 0000 | 00 | 00 |

TS store the temperature point of the IC. If the IC temperature reaches the temperature point the IC will trigger the thermal roll off and will decrease the current as TROF set percentage.

TROF percentage of output current
00 100\%
01 75\%
10 55\%
11 30\%

TS Temperature Point, Thermal roll off start point
$00 \quad 140^{\circ} \mathrm{C}$
$01 \quad 120^{\circ} \mathrm{C}$
$10 \quad 100^{\circ} \mathrm{C}$
$11 \quad 90^{\circ} \mathrm{C}$

Table 14 25h Spread Spectrum Register

| Bit | D7:D6 | D5 | D4 | D3:D2 | D1:D0 |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Name | SYNC | - | SSP | RNG | CLT |
| Default | 00 | 0 | 0 | 00 | 00 |

When SYNC bits are set to "11", the IS31FL3743A is configured as the master clock source and the SYNC pin will generate a clock signal distributed to the clock slave devices. To be configured as a clock slave device and accept an external clock input the slave device's SYNC bits must be set to "10".
When SSP enable, the spread spectrum function will be enabled and the RNG \& CLT bits will adjust the range and cycle time of spread spectrum function.

## SYNC Enable of SYNC function

0x Disable SYNC function, internal 30k $\Omega$ pull-low
10 Slave, clock input
11 Master, clock output

| SSP | Spread spectrum function enable |
| :--- | :--- |
| 0 | Disable |
| 1 | Enable |
|  |  |
| RNG | Spread spectrum range |
| 00 | $\pm 5 \%$ |
| 01 | $\pm 15 \%$ |
| 10 | $\pm 24 \%$ |
| 11 | $\pm 34 \%$ |

CLT Spread spectrum cycle time
$00 \quad 1980 \mu \mathrm{~s}$
$01 \quad 1200 \mu \mathrm{~s}$
$10 \quad 820 \mu \mathrm{~s}$
$11 \quad 660 \mu \mathrm{~s}$

## 2Fh Reset Register

Once user writes the Reset Register with OxAE, IS31FL3743A will reset all the IS31FL3743A registers to their default value. On initial power-up, the IS31FL3743A registers are reset to their default values for a blank display.

## APPLICATION INFORMATION



Figure 12 Scanning Timing

## SCANING TIMING

As shown in Figure 12 above, the SW1~SW11 is turned on by serial, LED is driven 11 by 11 within the SWx ( $x=1 \sim 11$ ) on time (SWx, $x=1 \sim 11$ is source and it is high when LED on), including the non-overlap blanking time during scan, the duty cycle of SWx (active high, $x=1 \sim 11$ ) is:

$$
\begin{equation*}
\text { Duty }=\frac{33 \mu s}{(33 \mu s+0.83 \mu s+0.3 \mu s)} \times \frac{1}{11}=\frac{1}{11.377} \tag{2}
\end{equation*}
$$

Where $33 \mu \mathrm{~s}$ is tscan, the period of scanning and $0.83 \mu \mathrm{~s}$ is $\mathrm{t}_{\mathrm{nol}}$, the non-overlap time and $0.3 \mu \mathrm{~s}$ is the CSy delay time.

## PWM CONTROL

After setting the lout and GCC, the brightness of each LEDs (LED average current (lled)) can be modulated with 256 steps by PWM Register, as described in Formula (1).

$$
\begin{equation*}
I_{L E D}=\frac{P W M}{256} \times I_{\text {OUT (PEAK })} \times \text { Duty } \tag{1}
\end{equation*}
$$

Where PWM is PWM Registers (PG0, 00h~B3h /PG1, 01h~C6h) data showing in Table 7.

For example, in Figure 1, if RISET= $10 \mathrm{k} \Omega, \mathrm{PWM}=255$, and GCC $=255$, Scaling $=255$, then

$$
\begin{gathered}
I_{\text {OUT (PEAK ) }}=\frac{343}{10 \mathrm{k} \Omega} \times \frac{255}{256} \times \frac{255}{256}=34 \mathrm{~mA} \\
I_{L E D}=34 \mathrm{~mA} \times \frac{1}{11.377} \times \frac{P W M}{256}
\end{gathered}
$$

Writing new data continuously to the registers can modulate the brightness of the LEDs to achieve a breathing effect.

## GAMMA CORRECTION

In order to perform a better visual LED breathing effect we recommend using a gamma corrected PWM value to set the LED intensity. This results in a reduced number of steps for the LED intensity setting, but causes the change in intensity to appear more linear to the human eye.

Gamma correction, also known as gamma compression or encoding, is used to encode linear luminance to match the non-linear characteristics of display. Since the IS31FL3743A can modulate the brightness of the LEDs with 256 steps, a gamma correction function can be applied when computing each subsequent LED intensity setting such that the changes in brightness matches the human eye's brightness curve.

Table 1532 Gamma Steps with 256 PWM Steps

| $\mathrm{C}(0)$ | $\mathrm{C}(1)$ | $\mathrm{C}(2)$ | $\mathrm{C}(3)$ | $\mathrm{C}(4)$ | $\mathrm{C}(5)$ | $\mathrm{C}(6)$ | $\mathrm{C}(7)$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0 | 1 | 2 | 4 | 6 | 10 | 13 | 18 |
| $\mathrm{C}(8)$ | $\mathrm{C}(9)$ | $\mathrm{C}(10)$ | $\mathrm{C}(11)$ | $\mathrm{C}(12)$ | $\mathrm{C}(13)$ | $\mathrm{C}(14)$ | $\mathrm{C}(15)$ |
| 22 | 28 | 33 | 39 | 46 | 53 | 61 | 69 |
| $\mathrm{C}(16)$ | $\mathrm{C}(17)$ | $\mathrm{C}(18)$ | $\mathrm{C}(19)$ | $\mathrm{C}(20)$ | $\mathrm{C}(21)$ | $\mathrm{C}(22)$ | $\mathrm{C}(23)$ |
| 78 | 86 | 96 | 106 | 116 | 126 | 138 | 149 |
| $\mathrm{C}(24)$ | $\mathrm{C}(25)$ | $\mathrm{C}(26)$ | $\mathrm{C}(27)$ | $\mathrm{C}(28)$ | $\mathrm{C}(29)$ | $\mathrm{C}(30)$ | $\mathrm{C}(31)$ |
| 161 | 173 | 186 | 199 | 212 | 226 | 240 | 255 |



Figure 13 Gamma Correction (32 Steps)
Choosing more gamma steps provides for a more continuous looking breathing effect. This is useful for very long breathing cycles. The recommended configuration is defined by the breath cycle T . When $\mathrm{T}=1 \mathrm{~s}$, choose 32 gamma steps, when $\mathrm{T}=2 \mathrm{~s}$, choose 64 gamma steps. The user must decide the final number of gamma steps not only by the LED itself, but also based on the visual performance of the finished product.
Table 1664 Gamma Steps with 256 PWM Steps

| $\mathrm{C}(0)$ | $\mathrm{C}(1)$ | $\mathrm{C}(2)$ | $\mathrm{C}(3)$ | $\mathrm{C}(4)$ | $\mathrm{C}(5)$ | $\mathrm{C}(6)$ | $\mathrm{C}(7)$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0 | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
| $\mathrm{C}(8)$ | $\mathrm{C}(9)$ | $\mathrm{C}(10)$ | $\mathrm{C}(11)$ | $\mathrm{C}(12)$ | $\mathrm{C}(13)$ | $\mathrm{C}(14)$ | $\mathrm{C}(15)$ |
| 8 | 10 | 12 | 14 | 16 | 18 | 20 | 22 |
| $\mathrm{C}(16)$ | $\mathrm{C}(17)$ | $\mathrm{C}(18)$ | $\mathrm{C}(19)$ | $\mathrm{C}(20)$ | $\mathrm{C}(21)$ | $\mathrm{C}(22)$ | $\mathrm{C}(23)$ |
| 24 | 26 | 29 | 32 | 35 | 38 | 41 | 44 |
| $\mathrm{C}(24)$ | $\mathrm{C}(25)$ | $\mathrm{C}(26)$ | $\mathrm{C}(27)$ | $\mathrm{C}(28)$ | $\mathrm{C}(29)$ | $\mathrm{C}(30)$ | $\mathrm{C}(31)$ |
| 47 | 50 | 53 | 57 | 61 | 65 | 69 | 73 |
| $\mathrm{C}(32)$ | $\mathrm{C}(33)$ | $\mathrm{C}(34)$ | $\mathrm{C}(35)$ | $\mathrm{C}(36)$ | $\mathrm{C}(37)$ | $\mathrm{C}(38)$ | $\mathrm{C}(39)$ |
| 77 | 81 | 85 | 89 | 94 | 99 | 104 | 109 |
| $\mathrm{C}(40)$ | $\mathrm{C}(41)$ | $\mathrm{C}(42)$ | $\mathrm{C}(43)$ | $\mathrm{C}(44)$ | $\mathrm{C}(45)$ | $\mathrm{C}(46)$ | $\mathrm{C}(47)$ |
| 114 | 119 | 124 | 129 | 134 | 140 | 146 | 152 |
| $\mathrm{C}(48)$ | $\mathrm{C}(49)$ | $\mathrm{C}(50)$ | $\mathrm{C}(51)$ | $\mathrm{C}(52)$ | $\mathrm{C}(53)$ | $\mathrm{C}(54)$ | $\mathrm{C}(55)$ |
| 158 | 164 | 170 | 176 | 182 | 188 | 195 | 202 |
| $\mathrm{C}(56)$ | $\mathrm{C}(57)$ | $\mathrm{C}(58)$ | $\mathrm{C}(59)$ | $\mathrm{C}(60)$ | $\mathrm{C}(61)$ | $\mathrm{C}(62)$ | $\mathrm{C}(63)$ |
| 209 | 216 | 223 | 230 | 237 | 244 | 251 | 255 |



Figure 14 Gamma Correction (64 Steps)
Note: The data of 32 gamma steps is the standard value and the data of 64 gamma steps is the recommended value.

## OPERATING MODE

IS31FL3743A can only operate in PWM Mode. The brightness of each LED can be modulated with 256 steps by PWM registers. For example, if the data in PWM Register is "0000 0100", then the PWM is the fourth step.
Writing new data continuously to the registers can modulate the brightness of the LEDs to achieve a breathing effect.

## OPEN/SHORT DETECT FUNCTION

IS31FL3743A has open and short detect bit for each LED.
By setting the OSD bits of the Configuration Register (PG2, 00h) from " 00 " to " 01 " or ' 10 ', the LED Open/short Register will start to store the open/short information and after at least 2 scanning cycles and the MCU can get the open/short information by reading the $03 \mathrm{~h} \sim 23 \mathrm{~h}$, for those dots are turned off via LED On/Off Registers (PG0, 00h~17h), the open/short data will not get refreshed when setting the OSD bit of the Configuration Register.

The two configurations need to set before setting the OSD bits:

```
1 0x0F\leqGCC\leq0x40, 02h=0x00
2 0x01\leqGCC\leq0x40,02h=0x30
```

Where GCC is the Global Current Control Register (PG2, 01h) and both case 1 or two can get the correct open and short information. 02h is the Pull Down/UP Resistor Selection Register and $0 \times 30$ is to enable the SWx pull-up function.
The detect action is one-off event and each time before reading out the open/short information, the OSD bit of the Configuration Register (PG3, OOh) need to be set from " 0 " to "1" (clear before set operation).

## DE-GHOST FUNCTION

The "ghost" term is used to describe the behavior of an LED that should be OFF but instead glows dimly when another LED is turned ON. A ghosting effect typically can occur when multiplexing LEDs. In matrix architecture any parasitic capacitance found in the constant-current outputs or the PCB traces to the LEDs may provide sufficient current to dimly light an LED to create a ghosting effect.
To prevent this LED ghost effect, the IS31FL3743A has integrated Pull down resistors for each SWx ( $x=1 \sim 11$ ) and Pull up resistors for each CSy ( $y=1 \sim 18$ ). Select the right SWx Pull down resistor (PG2, 02h) and CSy Pull up resistor (PG2, 02h) which eliminates the ghost LED for a particular matrix layout configuration.

Typically, selecting the $2 k \Omega$ will be sufficient to eliminate the LED ghost phenomenon.

The SWx Pull down resistors and CSy Pull up resistors are active only when the CSy/SWx output working the OFF state and therefore no power is lost through these resistors.

## SHUTDOWN MODE

Shutdown mode can be used as a means of reducing power consumption. During shutdown mode all registers retain their data.

## Software Shutdown

By setting SSD bit of the Configuration Register (PG2, 00 h ) to " 0 ", the IS31FL3743A will operate in software shutdown mode. When the IS31FL3743A is in software shutdown, all current sources are switched off, so that the matrix is blanked. All registers can be operated. Typical current consume is $1.3 \mu \mathrm{~A}$.

## Hardware Shutdown

The chip enters hardware shutdown when the SDB pin is pulled low. All analog circuits are disabled during hardware shutdown, typical the current consume is $1.3 \mu \mathrm{~A}$.
The chip releases hardware shutdown when the SDB pin is pulled high. During hardware shutdown state Function Register can be operated.

If VCC has risk drop below 1.75 V but above 0.1 V during SDB pulled low, please re-initialize all Function Registers before SDB pulled high.

## LAYOUT

As described in external resistor ( RISET ), the chip consumes lots of power. Please consider below factors when layout the PCB.

1. The $\mathrm{V}_{\mathrm{cc}}$ (PVCC, AVCC) capacitors need to close to the chip and the ground side should well connected to the GND of the chip.
2. Riset should be close to the chip and the ground side should well connect to the GND of the chip.
3. The thermal pad should connect to ground pins and the PCB should have the thermal pad too, usually this pad should have 16 or 25 via thru the PCB to other side's ground area to help radiate the heat. About the thermal pad size, please refer to the land pattern of each package.
4. The CSy pins maximum current is 34 mA ( $\mathrm{RISET}=10 \mathrm{k} \Omega$ ), and the SWx pins maximum current is larger, the width of the trace, SWx should have wider trace then CSy.

CLASSIFICATION REFLOW PROFILES

| Profile Feature | Pb-Free Assembly |
| :--- | :--- |
| Preheat \& Soak | $150^{\circ} \mathrm{C}$ |
| Temperature min (Tsmin) | $200^{\circ} \mathrm{C}$ |
| Temperature max (Tsmax) <br> Time (Tsmin to Tsmax) (ts) | $3^{\circ}-120$ seconds |
| Average ramp-up rate (Tsmax to Tp) | $217^{\circ} \mathrm{C}$ |
| Liquidous temperature (TL) <br> Time at liquidous (tL) | Max $260^{\circ} \mathrm{C}$ |
| Peak package body temperature (Tp)* max. |  |
| Time (tp)** within $5^{\circ} \mathrm{C}$ of the specified <br> classification temperature (Tc) | Max 30 seconds |
| Average ramp-down rate (Tp to Tsmax) | $6^{\circ} \mathrm{C} /$ second max. |
| Time $25^{\circ} \mathrm{C}$ to peak temperature | 8 minutes max. |



Figure 15 Classification Profile

PACKAGE INFORMATION

UQFN-40


RECOMMENDED LAND PATTERN
UQFN-40


## Note:

1. Land pattern complies to IPC-7351.
2. All dimensions in MM.
3. This document (including dimensions, notes \& specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown (eg. User's board manufacturing specs), user must determine suitability for use.

## REVISION HISTORY

| Revision | Detail Information | Date |
| :--- | :--- | :---: |
| A | Initial release | 2018.08 .06 |
| B | 1. Correct mistake in Table 6 and 11 <br> 2. Update Figure 8 | 2022.04 .07 |


[^0]:    Note 6: Guaranteed by design.

